L Number	Hits	Search Text	DB	Time stamp
Number		1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	TIC DAM	2004/04/04
1	0	heat with radiation same chip same bump and resist adj assist adj bonding	USPAT	12:26
2	0	heat with radiation same chip same bump	USPAT;	2004/04/04
_	-	and resist adj assist adj bonding	US-PGPUB; EPO; JPO	12:26
3	1	heat with radiation same chip and bump and resist adj assist adj bonding	USPAT; US-PGPUB;	2004/04/04 12:26
			EPO; JPO	0004/04/04
4	438	heat with radiation same chip and bump and bonding	USPAT; US-PGPUB; EPO; JPO	2004/04/04
5	83	heat with radiation same chip and bump same bond	USPAT; US-PGPUB; EPO; JPO	2004/04/04